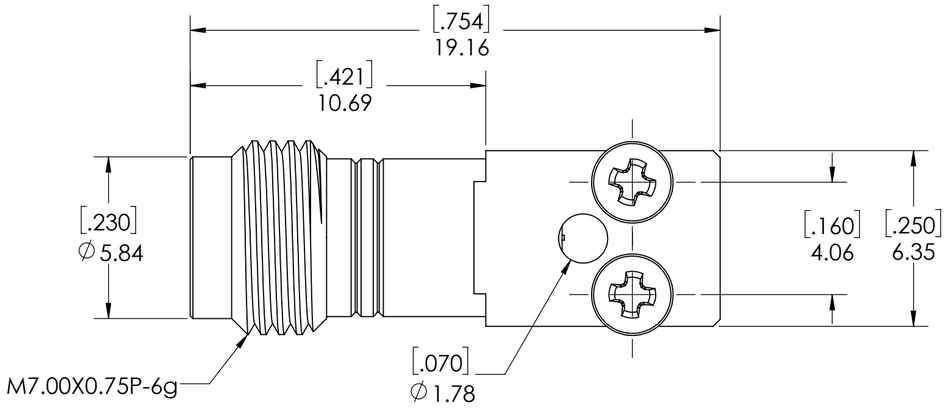
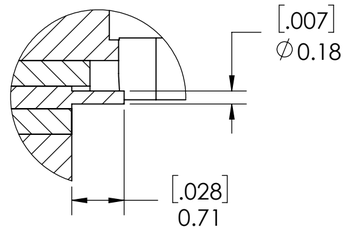
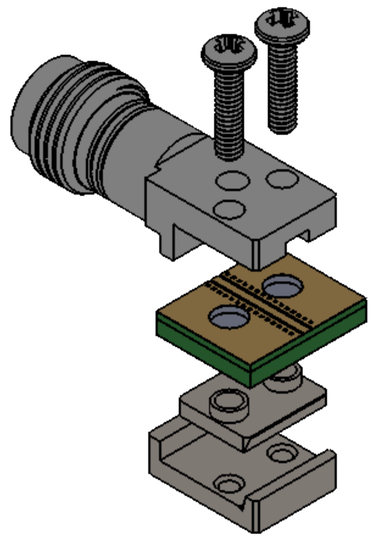
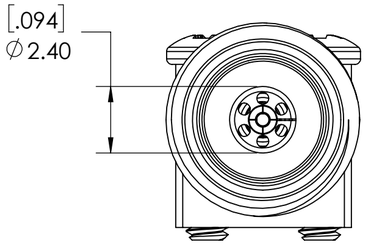
REVISIONS			
REV.	DESCRIPTION	DATE	DWN
-	INITIAL RELEASE	8/31/2020	FY

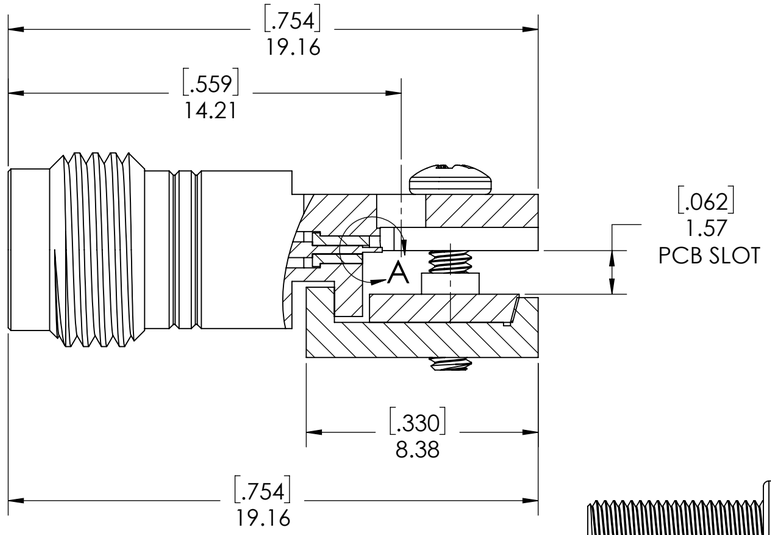


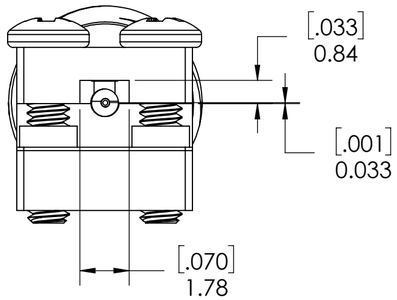


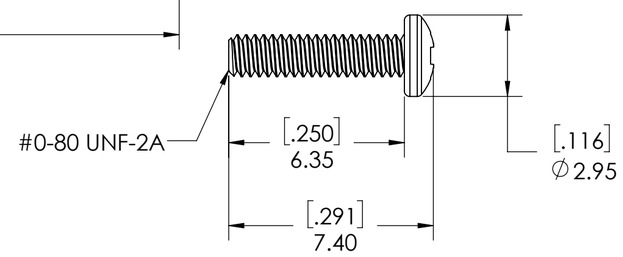
DETAIL A
SCALE 16 : 1

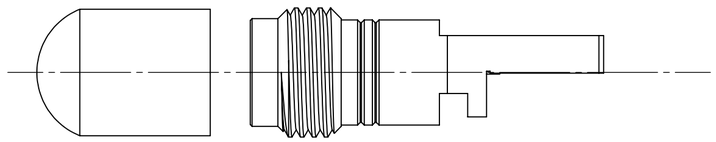












PROTECTION CAP

NOTE(S):
1. These characteristics are typical and for reference.
2. DYH: 60-20028-44070A
3. See sheet 2 for standard PCB interface definition.
4. See sheet 3 for non-standard PCB interface definition.

MATERIAL(S):

Body/Screws:
Stainless Steel
Locking Block:
Brass
Center Conductor:
Beryllium Copper
Insulator:
PCTFE, white
RoHS Compliant
Protective Cap:
Soft PVC
Color: Blue

ELECTRICAL(S):

Impedence: 50 Ohms Nominal
Frequency Range: DC to 50 GHz
VSWR: 1.30 max at 50 GHz
Working Voltage: 500 V RMS max @ Sea Level
Dielectric Withstand Voltage: 500 V RMS max.
Insulation Resistance: 5000 megaohms min.
Contact Resistance:
Initial:
Center Contact: 1.5 Milliohms max
Outer Contact: 0.8 Milliohms max

MECHANICAL(S):

Mating Characteristics:
Interface per MIL-STD-348
Force to Engage & Disengage:
Torque: 2 inch-pounds max
Longitudinal Force: NA
Connector Durability:
500 Cycles min.
Permeability: Less than 2.0 mu.
Center Contact Retention:
Axial Force: 6 pounds min.
Radial Force: NA

ENVIRONMENTAL(S):

Temperature Range: -55˚C to +85˚C
Moisture Resistance:
MIL-STD-202, Method 103, Test Condition B
Corrosion:
MIL-STD-202, Method 101, Test Condition B
Vibration:
MIL-STD-202, Method 204, Test Condition A
Shock:
MIL-STD-202, Method 213, Test Condition 1

FINISH(ES):

Body/Screw:
Passivated

Locking Block:
Nickel plating

Center Conductor:
Becu ,Gold Plating

APPLICABLE CARLISLE IT DOCUMENTS

WORK STANDARD	PROD INSTRUC	ASSY INSTRUC
NA	NA	NA
-		

TOLERANCES AND NOTES
EXCEPT AS NOTED

THIRD ANGLE PROJECTION

SCALE 8:1

DIMENSIONS ARE IN [INCHES] MM

ANGLES ±2°

.XX DECIMALS ±.063
.XXX DECIMALS ±.01

APPROVAL	INITIALS	DATE
DRAWN BY	FY	8/31/2020
CHECKED BY		
DESIGN ENG	PV	9/26/2019
APPR BY		

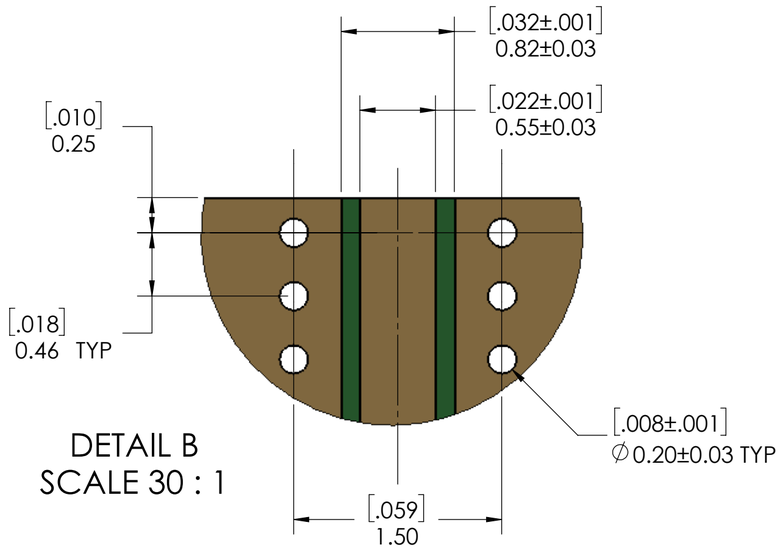
CARLISLE INTERCONNECT TECHNOLOGIES
Dongguan City, Guangdong P.R. China 523533

TITLE: Edge Launch, Narrow Body, Solderless, 2.4mm, Connector

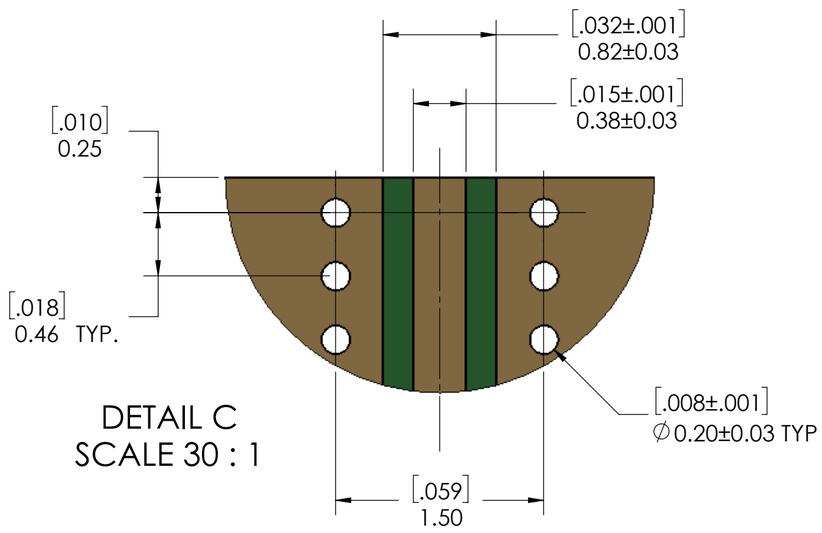
SCALE 8:1 | SUB-DIRECTORY/ _OUTLINE/ | SHEET 1 OF 3

SIZE C | DRAWING NO. TMB-E4F2-1L1-01 | REV. -

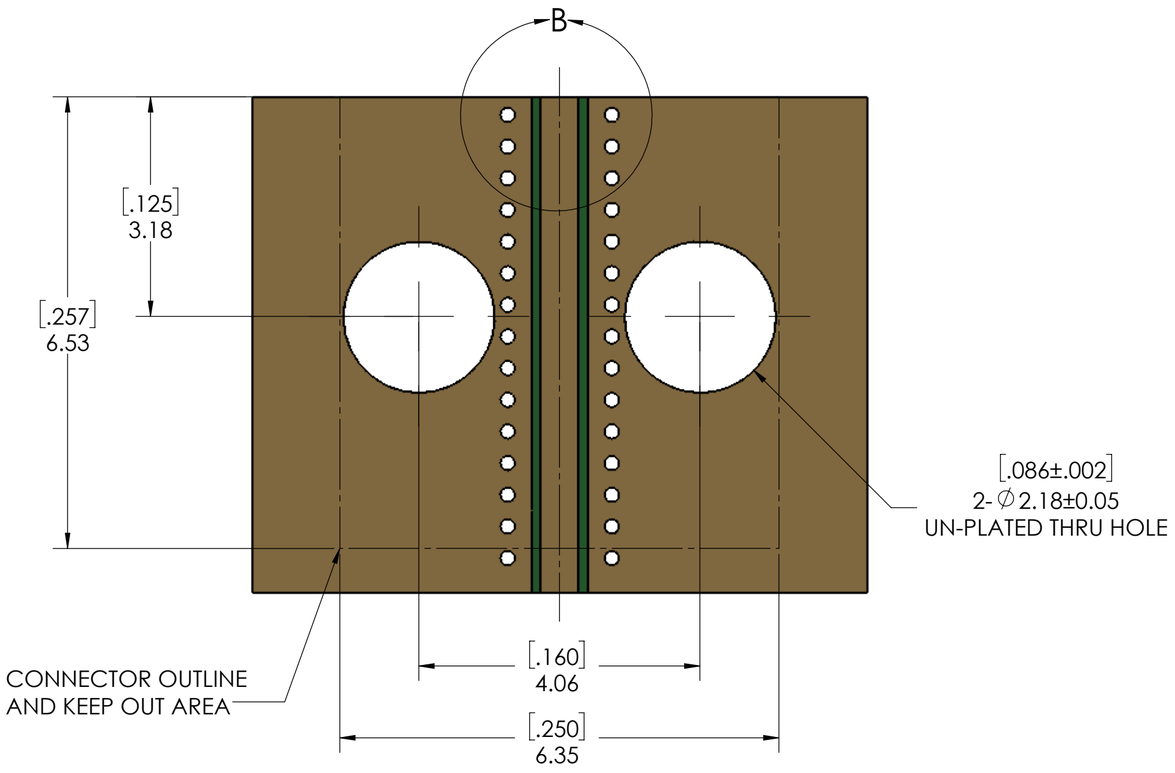
ENG–SW REV. E

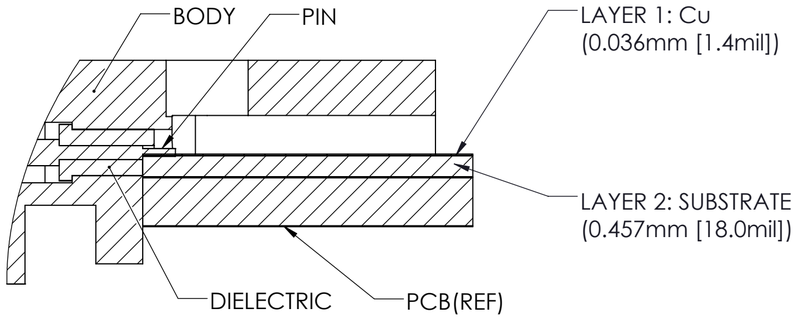


DETAIL B
SCALE 30 : 1

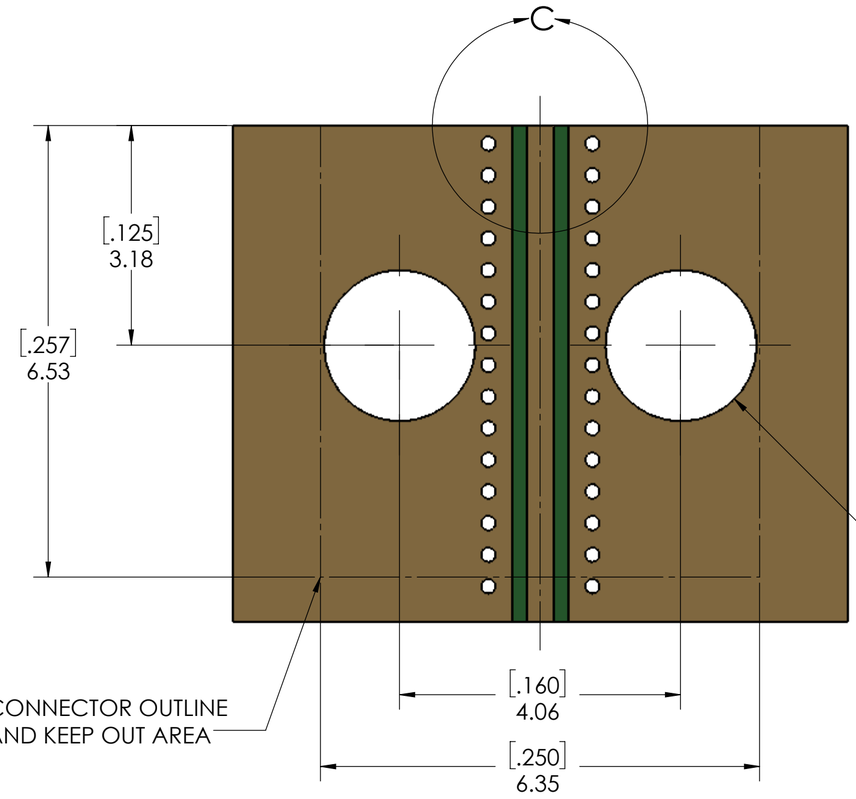


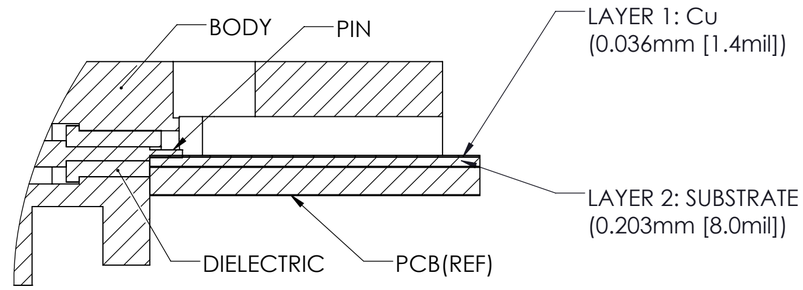
DETAIL C
SCALE 30 : 1





OPTION 1 : 0.457mm [18.0mil] THICK SUBSTRATE (LAYER 2)

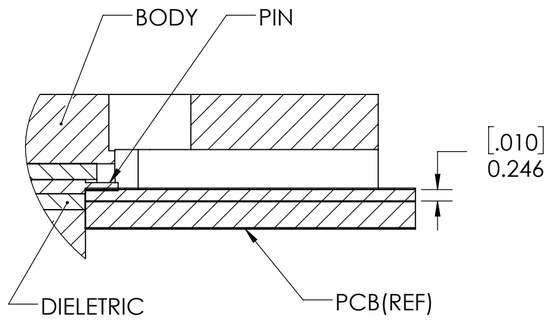




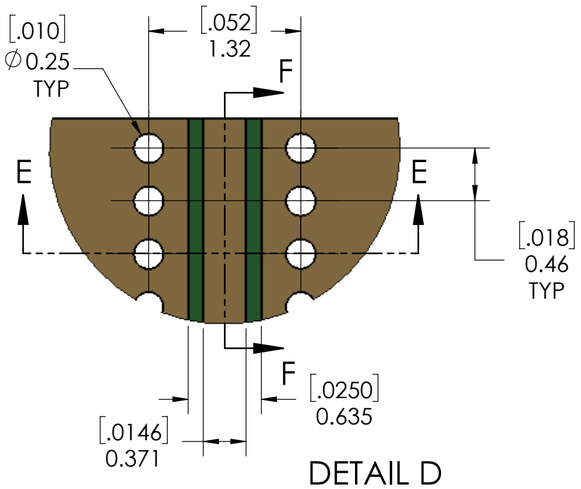
OPTION 2: 0.203mm [8.0mil] THICK SUBSTRATE (LAYER 2)

Standard PCB LAYOUT
(FOR RENFERENCE ONLY)

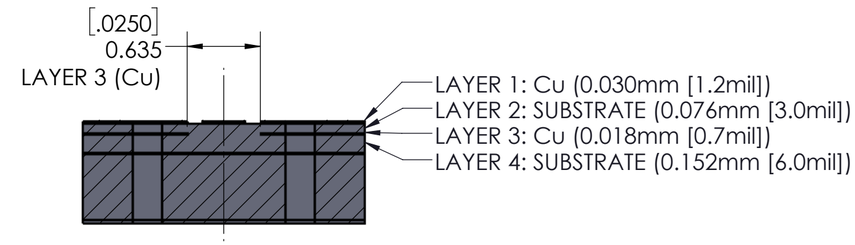
SCALE 10:1	SUB-DIRECTORY/		SHEET 2 OF 3
SIZE C	CAGE CODE	DRAWING NO. **TMB-E4F2-1L1-01**	REV. -



SECTION F-F

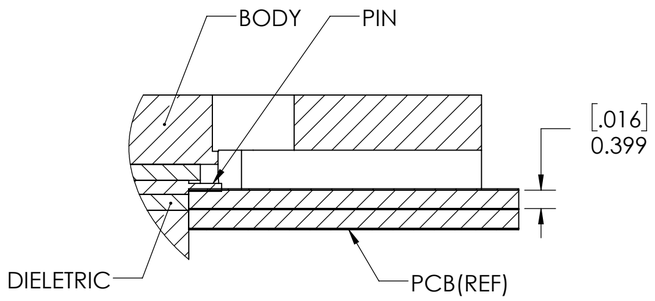


DETAIL D
SCALE 25:1

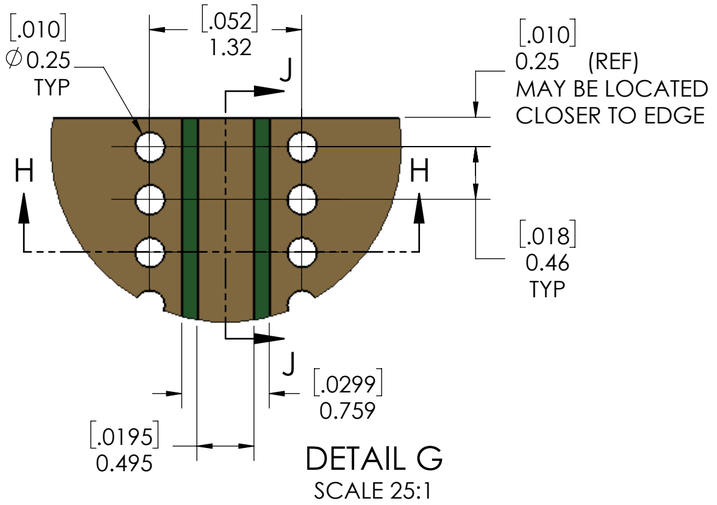


SECTION E-E

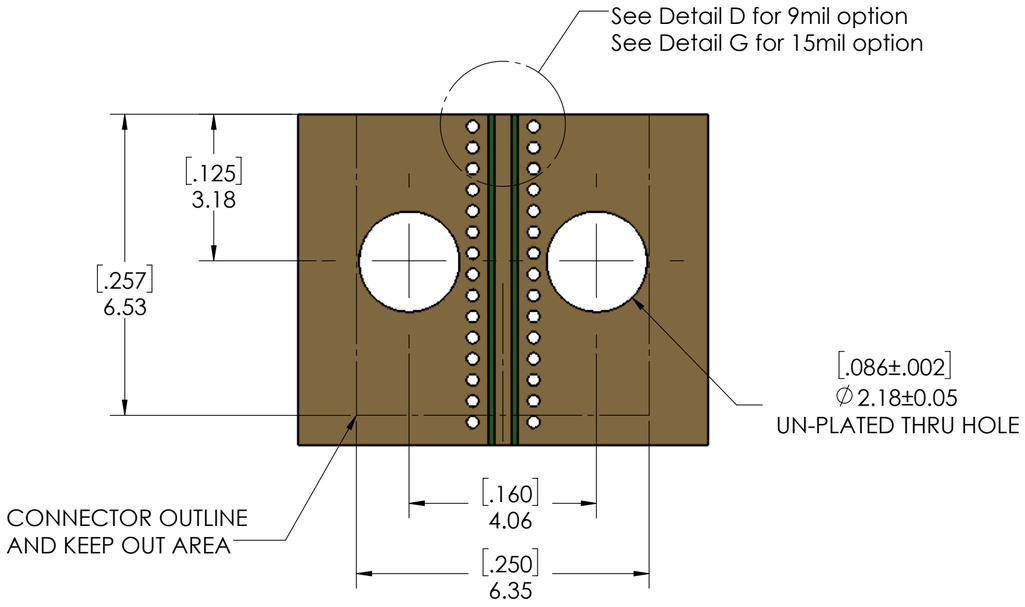
PCB 9mil Option
0.246mm [9.7mil] Dielectric
SUBSTRATE LAYERS 2 AND 4



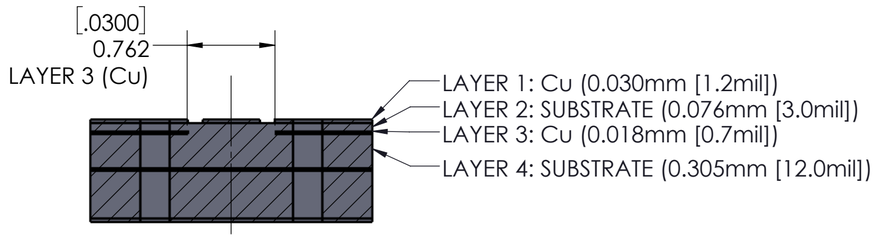
SECTION J-J



DETAIL G
SCALE 25:1



MOUNTING PATTERN



SECTION H-H

PCB 15mil Option
0.399mm [15.7mil] Dielectric
SUBSTRATE LAYERS 2 AND 4

PCB LAYOUT
Non-standard board stackup
(Reference)

SCALE	SUB-DIRECTORY/		SHEET 3 OF 3
10:1			
SIZE	CAGE CODE	DRAWING NO.	REV.
C		TMB-E4F2-1L1-01	-